



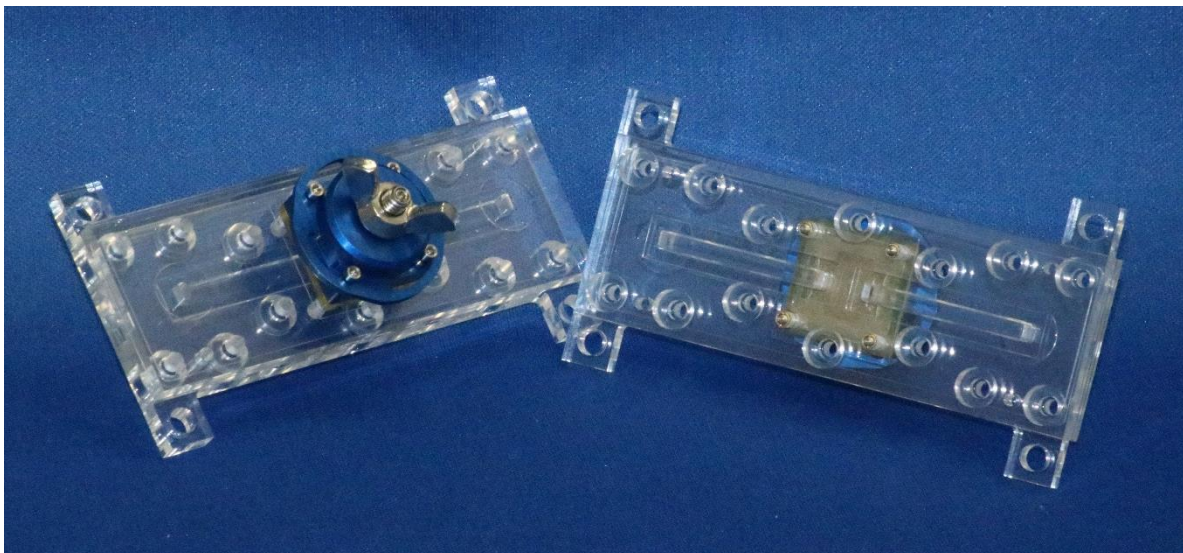
News Release: AIP socket announced at IMS2019

May 29, 2019

Paricon Technologies and RUPPtronik will both display a new style socket at the Boston IMS show in June that is designed for testing and characterizations of AIP (antenna-in-package) devices.

AIP is a new trend in IC packaging that allows the integration of all the complex RF components with the baseband circuitry into a complete self-contained module. This greatly facilitates the work of system integrators and reduces the overall size of the equipment. AIP applications will be found in automotive radars, and the IoT products.

The base of the socket has wave guides imbedded in its metal structure that feed directly to the antennae in the package. (The show demo base structure is made of acrylic to help explain the wave guide structures.) A PariPoser[®] elastomer connects the signal and power pads of the device to the test PCB (not shown).



These sockets are currently shipping with a lead time of 3-4 weeks.

For further information, please contact sales@paricon-tech.com or Bernd.Rupp@RUPPtronik.de.